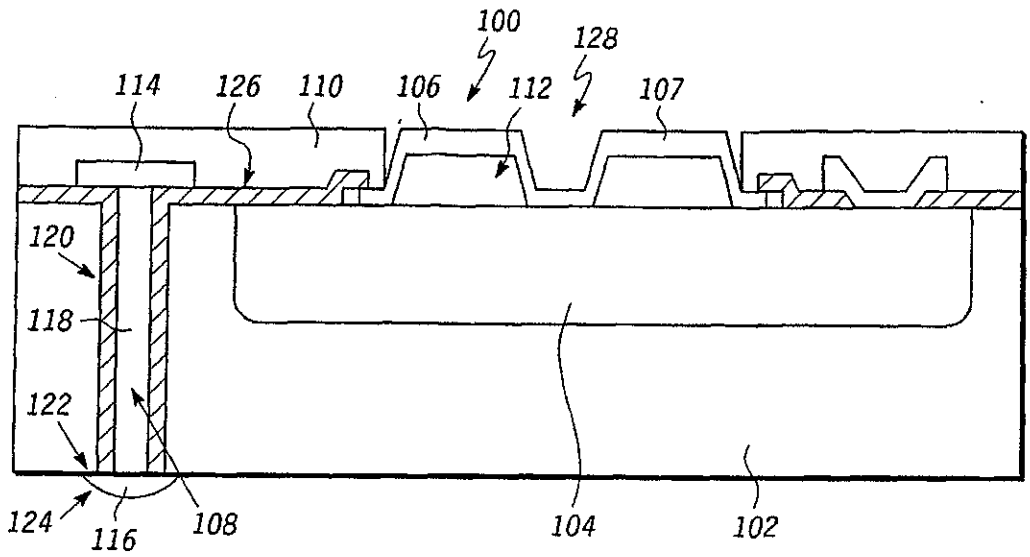

100
128
114
126
110
106
112
107
120
118
122
124
116
108
104
102

FIG. 1

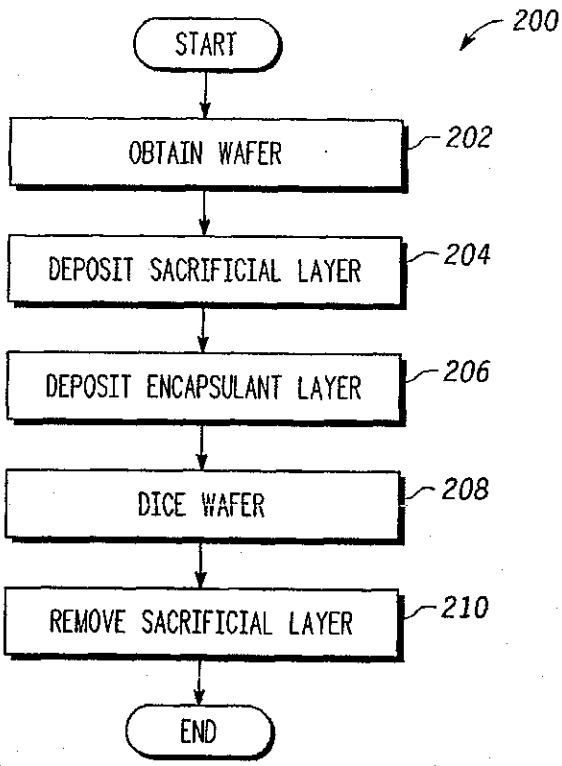

200
START
OBTAIN WAFER
202
DEPOSIT SACRIFICIAL LAYER
204
DEPOSIT ENCAPSULANT LAYER
206
DICE WAFER
208
REMOVE SACRIFICIAL LAYER
210
END

FIG. 2

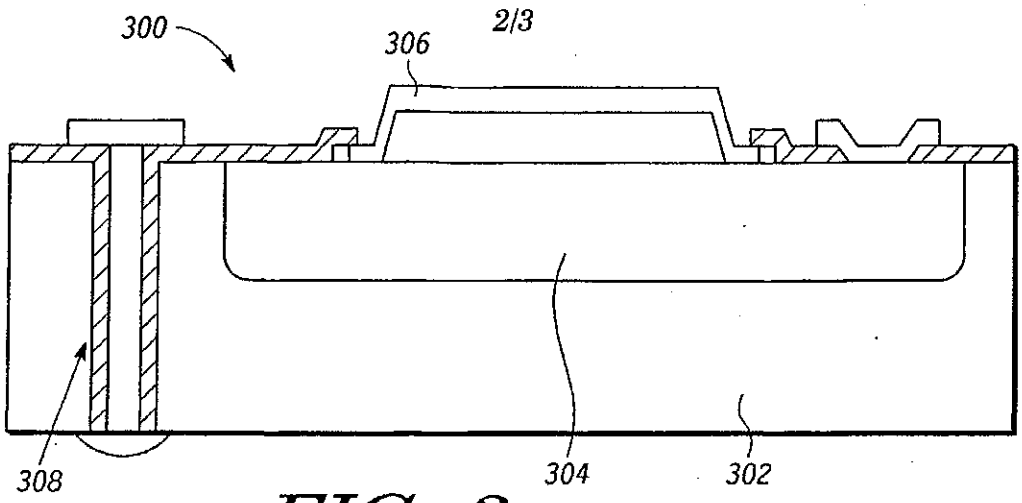


FIG. 3

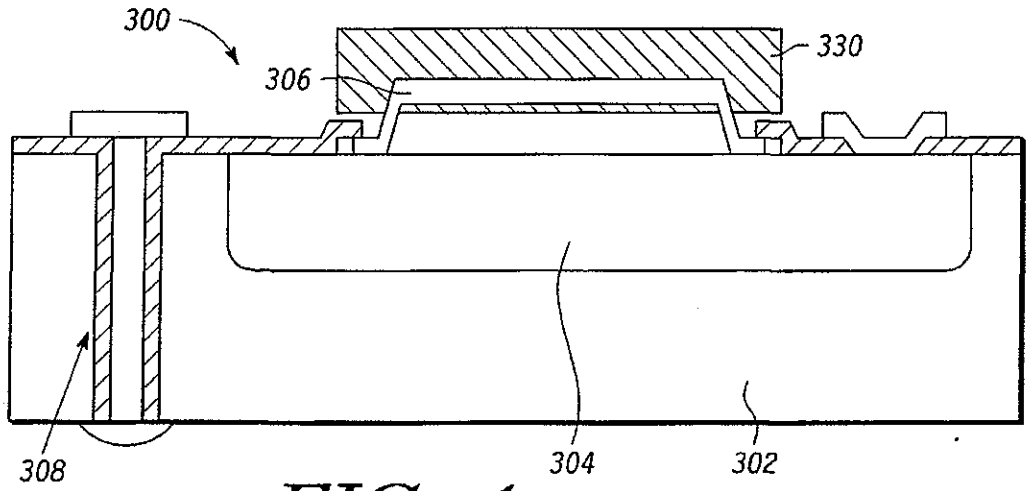


FIG. 4

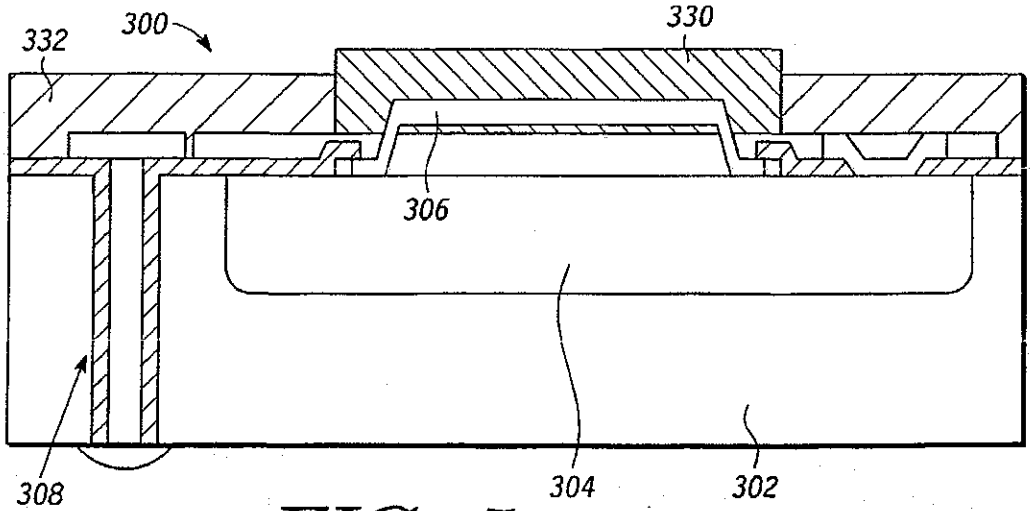


FIG. 5

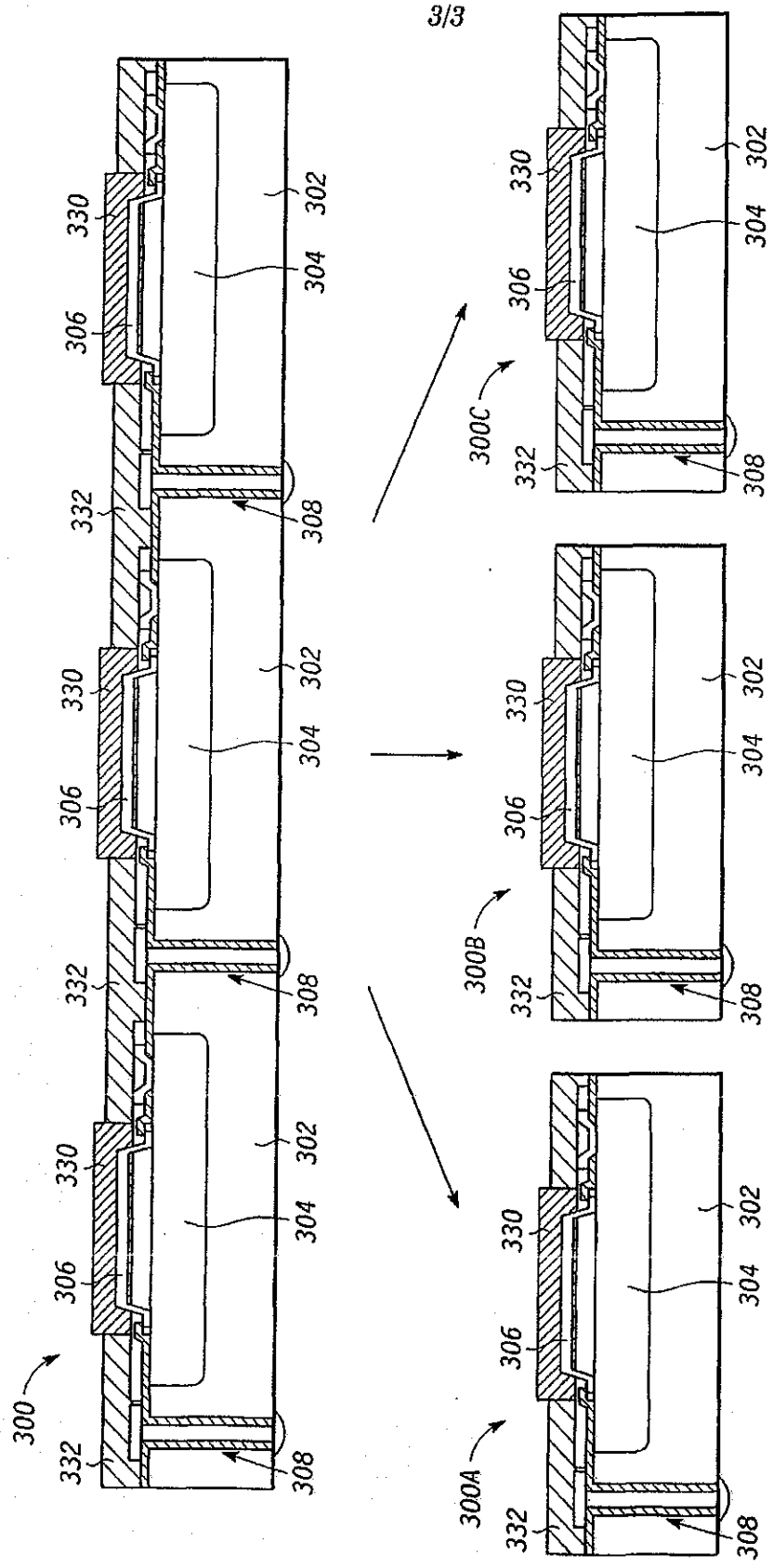


FIG. 6